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**CHENG et al.**(10) **Pub. No.: US 2024/0213167 A1**(43) **Pub. Date: Jun. 27, 2024**(54) **PACKAGE STRUCTURE HAVING LINE  
CONNECTED VIA PORTIONS***H01L 25/00* (2006.01)*H01L 25/065* (2006.01)*H01L 25/10* (2006.01)(71) Applicant: **Taiwan Semiconductor  
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Hsinchu (TW)(21) Appl. No.: **18/432,353**(22) Filed: **Feb. 5, 2024****Related U.S. Application Data**(60) Continuation of application No. 17/397,017, filed on  
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**ABSTRACT**

A package structure and method for forming the same are provided. The package structure includes a substrate having a front surface and a back surface, and a die formed on the back surface of the substrate. The package structure includes a first through via structure formed in the substrate, a conductive structure formed in a passivation layer over the front surface of the substrate. The conductive structure includes a via portion in direct contact with the substrate. The package structure includes a connector (formed over the via portion, wherein the connector includes an extending portion directly on a recessed top surface of the via portion.

